Annex to declaration of accreditation (scope of accreditation)
Normative document: EN ISO/IEC 17025:2017
Registration number: **L 388**

of **Eurofins MASER B.V.**
Enschede

This annex is valid from: **19-06-2025** to **01-10-2029** Replaces annex dated: **03-11-2022**

Location(s) where activities are performed under accreditation

Head Office

Auke Vleerstraat 26
7521 PG
Enschede
The Netherlands

Location	Abbreviation/ location code
Auke Vleerstraat 20/24 7521 PG Enschede The Netherlands	AV20/24
Auke Vleerstraat 26 7521 PG Enschede The Netherlands	AV26

No.	Material or product	Type of activity[1]	Internal reference number	Location
1	Electronic components	Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature, humidity and bias conditions	JESD22-A101 JESD22-A110	AV20/24
2		Exposure of electronic components to calibrated and controlled temperature and humidity conditions	JESD22-A102 JESD22-A118 IEC 60068-2-78	AV20/24

This annex has been approved by the Board of the Dutch Accreditation Council, on its behalf,

J.A.W.M. de Haas

[1] If there is a referral to a code starting with NAW, NAP, EA or IAF, this concerns a scheme mentioned on the RvA-BR010-lijst.
If no date or version number is mentioned for a normative document, the accreditation concerns the most current version of the document or scheme.

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No.	Material or product	Type of activity[1]	Internal reference number	Location
3	Electronic components	Exposure of electronic components to calibrated and controlled high temperature conditions	JESD22-A103 IEC 60068-2-2 MIL-STD-883, method 1008	AV20/24
4		Exposure of electronic components to calibrated and controlled alternating temperature conditions	JESD22-A104 IEC 60068-2-14 MIL-STD-883, method 1010	AV20/24
5		Exposure of heat-dissipating electronic components to calibrated and controlled alternating bias and alternating temperature conditions	JESD22-A105	AV20/24
6		Exposure of (non) heat-dissipating electronic components to calibrated and controlled temperature and bias conditions	JESD22-A108 AEC Q100-008	AV20/24, AV26
7		Exposure of electronic components to calibrated and controlled low temperature conditions	JESD22-A119 IEC 60068-2-1	AV20/24
8		Exposure of electronic components to calibrated and controlled alternating humidity, alternating temperature and bias conditions	JESD22-A100 IEC 60068-2-38 MIL-STD-883, method 1004	AV20/24
9		Exposure of bond wires of electronic components to calibrated and controlled pull forces	MIL-STD-883, method 2011 MIL-STD-750, method 2037.1 condition D	AV26
10		Exposure of bond wires, dies or solderballs of electronic components to calibrated and controlled shear forces	MIL-STD-883, method 2019 AEC Q100-001 AEC Q100-010 AEC Q101-003 JESD22-B116 JESD22-B117	AV26